WHAT IS CLAIMED IS:

1. A method of manufacturing a thin film semiconductor device comprising:

a preparatory step of preparing a manufacturing substrate having a characteristic capable of enduring a process for forming a thin film transistor and a product substrate having a characteristic suitable to direct mounting of the thin film transistor,

a bonding step of bonding the manufacturing substrate to the product substrate for supporting the product substrate at the back,

a formation step of forming at least a thin film transistor to the surface of the product substrate in a state reinforced with the manufacturing substrate, and

a separation step of separating the manufacturing substrate after use from the product substrate.

2. A method of manufacturing a thin film semiconductor device as claimed in claim 1, wherein the preparatory step comprises preparing the manufacturing substrate made of an inorganic material and a product substrate made of an organic substrate.

3. A method of manufacturing a thin film semiconductor device as claimed in claim 2, wherein the formation step comprises forming a moisture proof film on the surface of the product

substrate made of an organic material and then forming the thin film transistor thereon.

4. A method of manufacturing a thin film semiconductor device as claimed in claim 1, wherein the bonding step comprises bonding the manufacturing substrate to the product substrate by using adhesives coated in a releasable state.

5. A method of manufacturing a liquid crystal display device comprising:

a preparatory step of preparing a manufacturing substrate having a characteristic capable of enduring a process for forming a thin film transistor and a product substrate having a characteristic suitable to direct mounting of the thin film transistor,

a bonding step of bonding the manufacturing substrate to the product substrate for supporting the product substrate at the back,

a formation step of forming at least a thin film transistor and a pixel electrode to the surface of the product substrate in a state reinforced with the manufacturing substrate,

a separation step of separating the manufacturing substrate after use from the product substrate, and

an assembling step of joining an opposing substrate previously formed with opposing electrodes at a predetermined distance to the product substrate formed with the pixel electrodes

before or after the separation step, and injecting liquid crystals in the gap.

6. A method of manufacturing a liquid crystal display device as claimed in claim 5, wherein the preparatory step comprises preparing a manufacturing substrate made of an inorganic material and a product substrate made of an organic substrate,

7. A method of manufacturing a liquid crystal display device as claimed in claim 6, wherein the formation step comprises forming a moisture proof film on the surface of the product substrate made of an organic material and then forming the thin film transistor thereon.

8. A method of manufacturing a liquid crystal display device as claimed in claim 5, wherein the bonding step comprises bonding the manufacturing substrate to the product substrate by using adhesives coated in a releasable state.

9. A method of manufacturing an electroluminescence display device comprising:

a preparatory step of preparing a manufacturing substrate having a characteristic capable of enduring a process for forming a thin film transistor and a product substrate having a characteristic suitable to direct mounting of the thin film transistor,

a bonding step of bonding the manufacturing substrate to

the product substrate for supporting the product substrate at the back,

a formation step of forming at least a thin film transistor and an electroluminescence device to the surface of the product substrate in a state reinforced with the manufacturing substrate, and

a separation step of separating the manufacturing substrate after use from the product substrate.

10. A method of manufacturing an electroluminescence display device as claimed in claim 9, wherein the preparatory step comprises preparing a manufacturing substrate made of an inorganic material and a product substrate made of an organic substrate,

11. A method of manufacturing an electroluminescence display device as claimed in claim 10, wherein the forming step comprises forming a moisture proof film on the surface of the product substrate made of an organic material and then forming the thin film transistor and electroluminescence device thereon.

12. A method of manufacturing an electroluminescence display device as claimed in claim 9, wherein the bonding step comprises bonding the manufacturing substrate to the product substrate by using adhesives coated in a releasable state.

13. A thin film semiconductor device having a structure formed by using a manufacturing substrate having a characteristic

capable of enduring a process for forming a thin film transistor and a product substrate having a characteristic suitable to direct mounting of the thin film transistor, bonding the manufacturing substrate to the product substrate for supporting the product substrate at the back, forming at least a thin film transistor to the surface of the product substrate in a state reinforced with the manufacturing substrate, and separating the manufacturing substrate after use from the product substrate.

14. A thin film semiconductor device as claimed in claim 13, wherein a manufacturing substrate made of an inorganic material and a product substrate made of an organic material are used.

15. A thin film semiconductor device as claimed in claim 14, wherein a moisture proof film is formed on the surface of the product substrate made of an organic material and then a thin film transistor is formed thereon.

16. A liquid crystal display device having a structure formed by using a manufacturing substrate having a characteristic capable of enduring the process for forming a thin film transistor and a product substrate having a characteristic suitable to direct mounting of the thin film transistor, bonding the manufacturing substrate to the product substrate for supporting the product substrate at the back, forming a thin film transistor and a pixel electrode on the surface of the product substrate in a state

reinforced with the manufacturing substrate, joining an opposed substrate previously formed with opposing electrodes joined to the product substrate formed with the pixel electrode at a predetermined gap and possessing liquid crystals in the gap and separating the manufacturing substrate after use from the product substrate.

17. A liquid crystal display device as claimed in claim 16, wherein the manufacturing substrate made of an inorganic material and a product substrate made of an organic material are used.

18. A liquid crystal display device as claimed in claim 17, wherein a moisture proof film is formed on the surface of the product substrate made of an organic material and then the thin film transistor is formed thereon.

19. An electroluminescence display device having a structure formed by using a manufacturing substrate having a characteristic capable of enduring the process for forming a thin film transistor and a product substrate having a characteristic suitable to direct mounting of the thin film transistor, bonding the manufacturing substrate to the product substrate supporting the product substrate at the back, forming a thin film transistor and a electroluminescence display device on the surface of the product substrate in a state reinforced with the manufacturing substrate, and separating the

manufacturing substrate after use from the product substrate.

20. An electroluminescence display device as claimed in claim 19, wherein a manufacturing substrate made of an inorganic material and a product substrate made of an organic material are used.

21. An electroluminescence display device as claimed in claim 20, wherein a moisture proof film is formed on the surface of the product substrate made of the organic material and then a thin film transistor and an electroluminescence display device are formed thereon.